

TOSHIBA RF POWER AMPLIFIER MODULE

S - A U 7 6

800MHz UHF POWER AMPLIFIER MODULE (AMPS)

- High Gain ($G_p=18.5\text{dB Min.}$)

MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
DC Supply Voltage	V_{DD}	10	V
DC Supply Voltage	V_{GG}	6	V
Input Power	P_i	17	mW
Operating Case Temperature Range	$T_{c(opr)}$	-35~100	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40~120	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Frequency	f_{range}	—	824	—	849	MHz
Output Power	P_o	$P_i = 13\text{dBmW}$, $V_{GG} = 4.5\text{V}$, $V_{DD} = 6.0\text{V}$	31.5	—	—	dBmW
Power Gain	G_p	$Z_G = Z_L = 50\Omega$ (Note 1)	18.5	—	—	dB
Current Drain	I_{DD}	$P_o = 31.0\text{dBmW}$ ($V_{GG} = \text{adjust}$), $V_{DD} = 6.0\text{V}$ $P_i = 13\text{dBmW}$, $Z_G = Z_L = 50\Omega$	—	—	420	mA
Current Gate	I_{GG}	$P_o = 31.5\text{dBmW}$ ($V_{GG} = \text{adjust}$), $V_{DD} = 6.0\text{V}$	—	—	100	μA
Input VSWR	$VSWR_{in}$	$P_i = 13\text{dBmW}$, $Z_G = Z_L = 50\Omega$	—	—	3	—
Load Mismatch	—	$P_i = 13\text{dBmW}$, $V_{GG} = 5.0\text{V}$, $V_{DD} = 8.5\text{V}$ VSWR LOAD 20 : 1 ALL PHASE, 10s	No Degradation			—
Stability	—	$P_i = 9\sim 17\text{dBmW}$, $V_{GG} = 0\sim 5.0\text{V}$ $V_{DD} = 5.2\sim 8.5\text{V}$ VSWR LOAD 3 : 1 (in band) ALL PHASE VSWR LOAD 10 : 1 (Out of band) ALL PHASE	All Spurious Outputs more than 60dB below desired signal			—
TX Noise	—	$P_i = 13\text{dBmW}$, $V_{GG} = 0\sim 5.0\text{V}$ $V_{DD} = 5.2\sim 8.5\text{V}$, $f = 869\sim 894\text{MHz}$ $BW = 30\text{kHz}$	—	—	-92	dBmW

(Note 1) : Voltage Apply Sequence (1) V_{DD} (2) V_{GG}

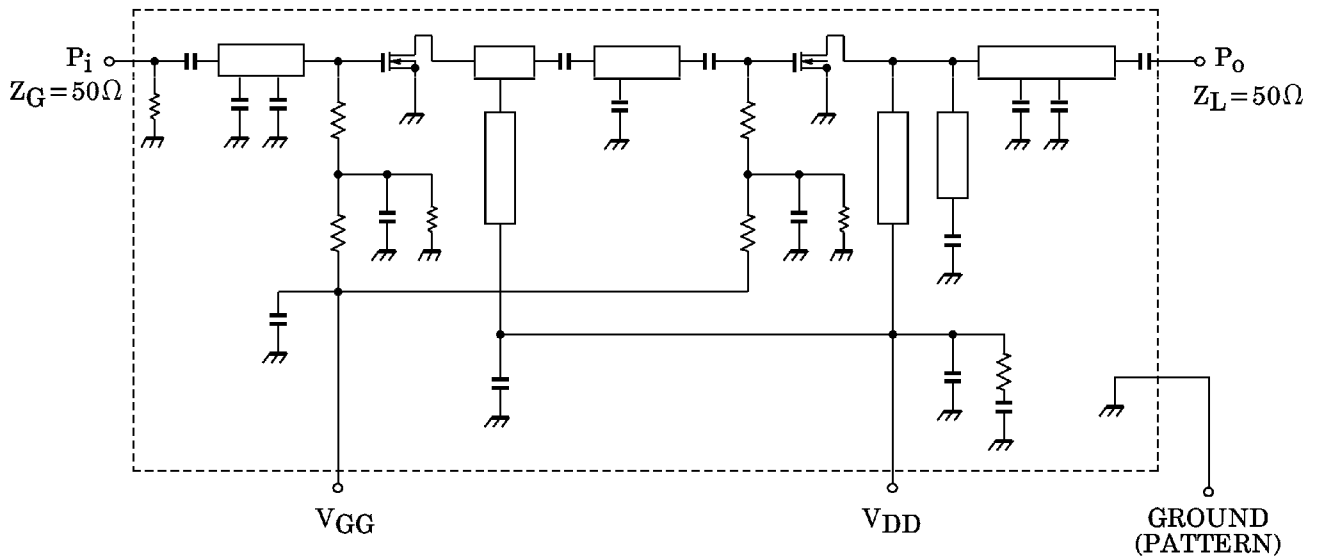
CAUTION

- This device is electrostatic sensitivity, please handle with caution.

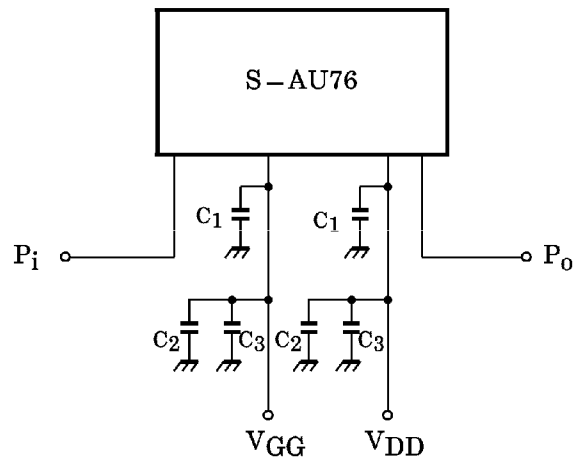
961001EAA2

- TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.

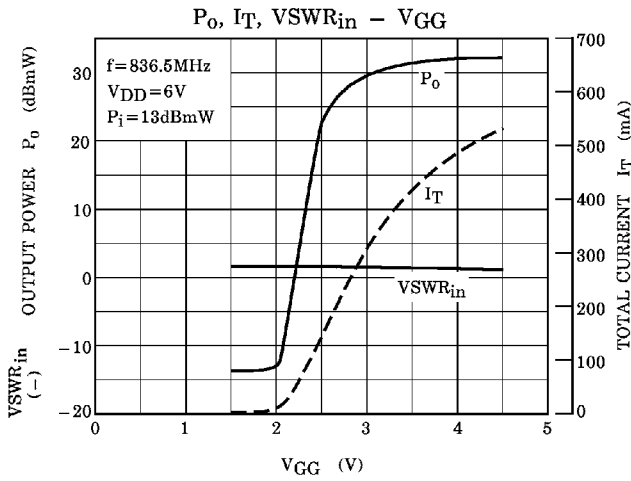
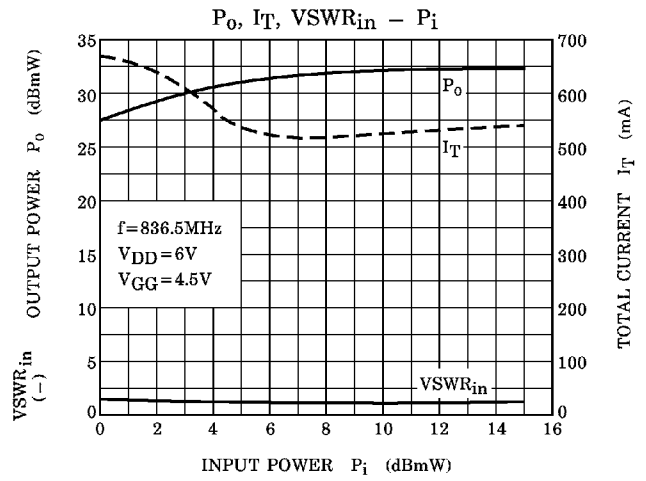
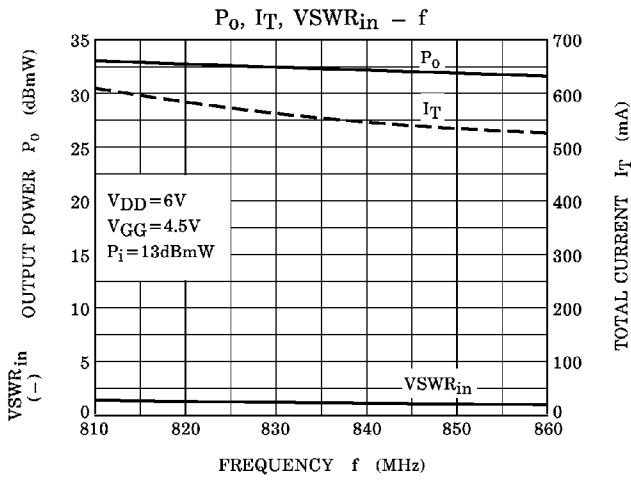
SCHEMATIC



TEST FIXTURE



- $C_1 : 1000\text{pF}$
- $C_2 : 0.1\mu\text{F}$
- $C_3 : 1\mu\text{F}$

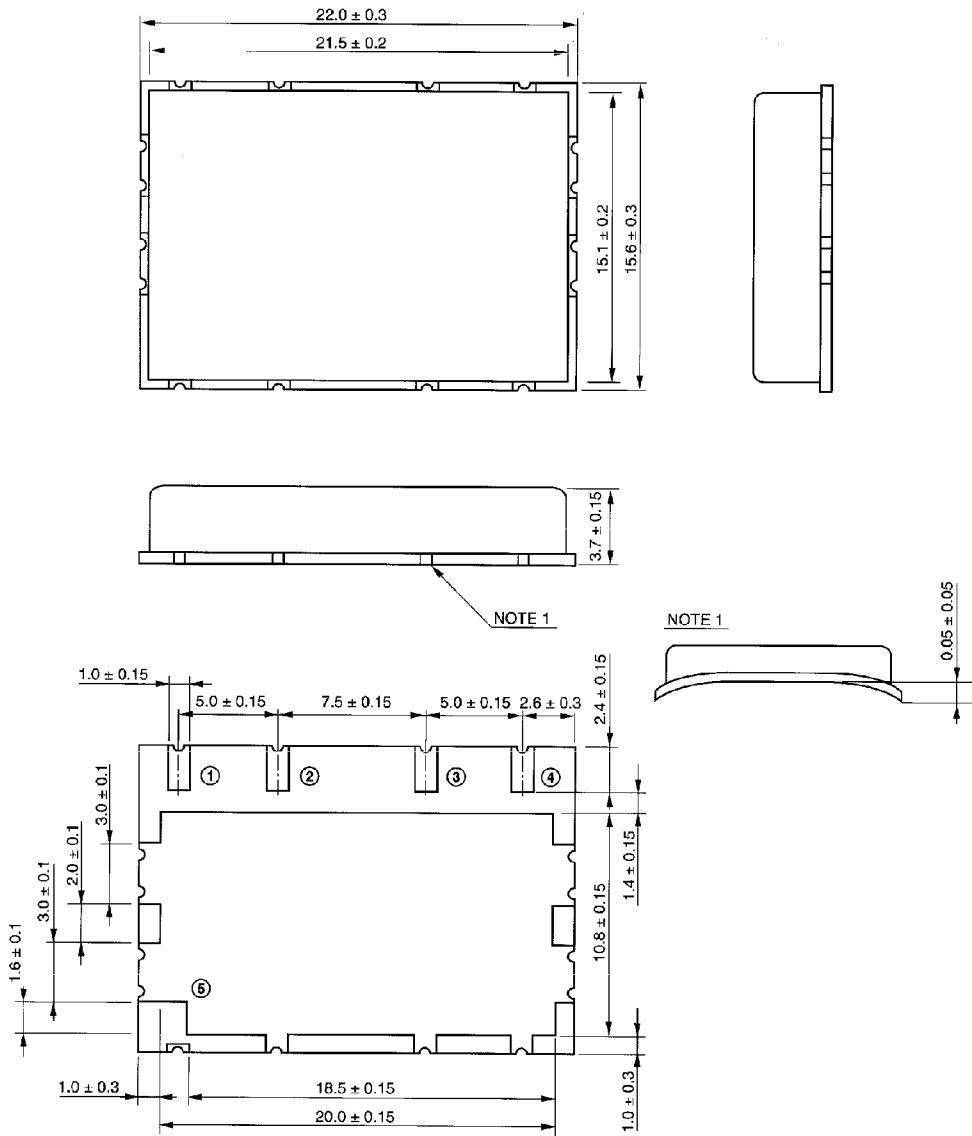


CAUTION

These are only typical curves and devices are not necessarily guaranteed at these curves.

OUTLINE DRAWING

Unit in mm



Weight : 1.8g

- ① INPUT
- ② VGG
- ③ VDD
- ④ OUTPUT
- ⑤ GROUND (PATTERN)

JEDEC	—
EIAJ	—
TOSHIBA	5-22P